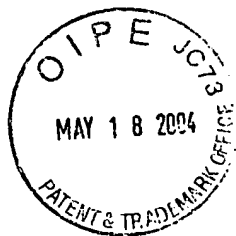


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Electronic Filing System (EFS) Data
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EFS ID: 61210
Application ID: 10774893
Title of Invention: LEADFRAME FOR SEMICONDUCTOR PACKAGE
First Named Inventor: HYUNG LEE
Domestic/Foreign Application: Domestic Application
Filing Date: 2004-02-09
Effective Receipt Date: 2004-05-18
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Filing Type:
Confirmation number: 8761
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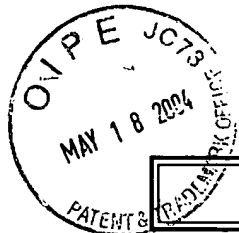
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Title of Invention	LEADFRAME FOR SEMICONDUCTOR PACKAGE									
<p>Application Number: 10/774893 </p> <p>Date: 2004-02-09</p> <p>First Named Applicant: HYUNG JU LEE</p> <p>Confirmation Number: 8761</p> <p>Attorney Docket Number: AMKOR006C</p>										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B. GARRED Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
MARK B. GARRED Registered Number: 34,823	/mbg/	Attorney								
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids2-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr></table>			Documents being submitted	Files	us-ids	ids2-usidst.xml		us-ids.dtd		us-ids.xsl
Documents being submitted	Files									
us-ids	ids2-usidst.xml									
	us-ids.dtd									
	us-ids.xsl									
Comments										



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

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Title of
Invention

LEADFRAME FOR SEMICONDUCTOR PACKAGE

Application Number: 10/774893
Confirmation Number: 8761
First Named Applicant: HYUNG LEE
Attorney Docket Number: AMKOR006C
Art Unit: 2811

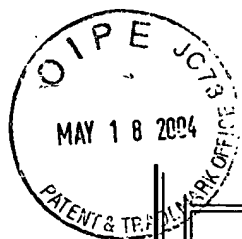


Search string: (5216278 or 5218231 or 5221642 or 5250841
or 5252853 or 5258094 or 5266834 or 5273938
or 5277972 or 5278446 or 5279029 or 5281849
or 5294897 or 5327008 or 5332864 or 5335771
or 5336931 or 5343076 or 5358905 or 5365106
or 5381042 or 5391439 or 5406124 or 5410180
or 5414299 or 5417905 or 5424576 or 5428248
or 5435057 or 5444301 or 5452511 or 5454905
or 5474958 or 5484274 or 5493151 or 5508556
or 5517056 or 5521429 or 5528076 or 5534467
or 5539251 or 5543657 or 5544412 or 5545923
or 5581122 or 5592019 or 5592025 or 5594274
or 5595934 or 5604376).pn.

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Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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Signature

Examiner Name	Date